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### (54) IMMERSION COOLING SYSTEM THAT ENABLES INCREASED HEAT FLUX AT HEAT-GENERATING COMPONENTS OF COMPUTING DEVICES

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#### (57)ABSTRACT

An immersion cooling system includes an immersion tank that is configured to retain dielectric working fluid and to hold a plurality of computing devices submerged in the dielectric working fluid. The immersion cooling system also includes a condenser that is configured to cause condensation of vaporized working fluid. The immersion cooling system also includes a subcooling heat exchanger that is in fluid communication with a coolant source. The coolant source provides coolant having a coolant temperature that is lower than a boiling point of the dielectric working fluid. The subcooling heat exchanger is positioned so that heat transfer can occur between the dielectric working fluid and the subcooling heat exchanger. The immersion cooling system also includes a control system that controls how much of the coolant flows into the subcooling heat exchanger based at least in part on a temperature of the dielectric working fluid.

